

Features

- · Excellent Stability and Uniformity
- High Dense Cell Design for Extremely Low R_{DS(ON)}
- Epoxy Meets UL 94 V-0 Flammability Rating
- · Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

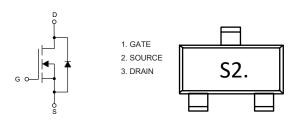
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance:80°C/W Junction to Ambient(Steady-State)⁽²⁾

Parameter	Symbol	Rating	Unit		
Drain-Source Voltage	V _{DS}	20	V		
Gate-Source Volltage	V _{GS}	±8	V		
Continuous Drain Current	T _A =25°C		3.0	۸	
	T _A =100°C	l _D	1.9	Α	
Pulsed Drain Current ⁽³⁾	•	I _{DM}	10	Α	
Total Power Dissipation ⁽⁴⁾		P _D	1.56	W	

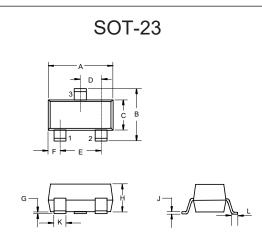
Note:

- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. The value of $R_{\theta JA}$ is measured with the device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ t≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4. P_D is based on max. junction temperature, using junction to ambient thermal resistance.

Internal Structure and Marking Code

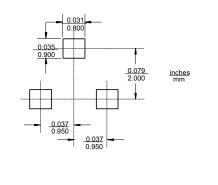


N-Channel Enhancement Mode Field Effect Transistor



DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	NOTE
Α	0.110	0.120	2.80	3.04	
В	0.083	0.104	2.10	2.64	
С	0.047	0.055	1.20	1.40	
D	0.034	0.041	0.85	1.05	
Е	0.067	0.083	1.70	2.10	
F	0.018	0.024	0.45	0.60	
G	0.0004	0.006	0.01	0.15	
Н	0.035	0.043	0.90	1.10	
J	0.003	0.007	0.08	0.18	
K	0.012	0.020	0.30	0.51	
L	0.007	0.020	0.20	0.50	

Suggested Solder Pad Layout



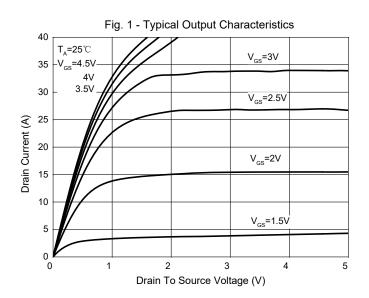


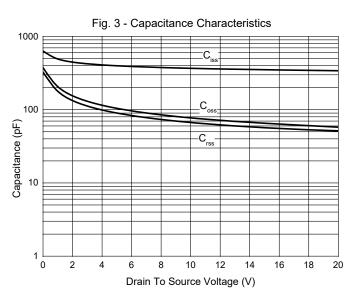
Electrical Characteristics @ 25°C (Unless Otherwise Specified)

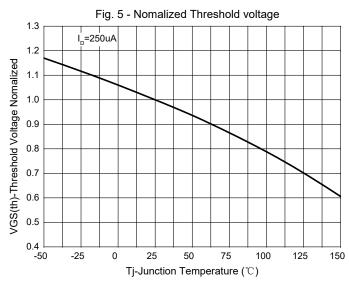
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static Characteristics			1			I	
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V _{GS} =0V, I _D =250μA	20			V	
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±8V			±100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} =0V			1	μA	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	0.65		1.2	V	
		V _{GS} =4.5V, I _D =4.3A		21	27		
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =2.5V, I _D =3A	28 3		37	mΩ	
		V _{GS} =1.8V, I _D =2A		51	67	-	
Gate Resistance	R_g	F=1 MHz, Open drain		3.4		Ω	
Diode Characteristics			-	·	ı	1	
Continuous Body Diode Current	Is				0.94	Α	
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =0.94A			1.2	V	
Reverse Recovery Time	t _{rr}	I _F =3.6A, dI _F /dt=100A/μs		12.2		ns	
Reverse Recovery Charge	Q _{rr}	i i=-3.0Λ, αιε/αι-100Λ/μ5		3.2		nC	
Dynamic Characteristics			·				
Input Capacitance	C _{iss}			388			
Output Capacitance	C _{oss}	V _{DS} =10V,V _{GS} =0V,f=1MHz		77		pF	
Reverse Transfer Capacitance	C _{rss}			68			
Total Gate Charge	Qg			5.5			
Gate-Source Charge	Q _{gs}	V _{DS} =10V,V _{GS} =4.5V,I _D =3.6A		0.63		nC	
Gate-Drain Charge	Q_{gd}			1.7			
Turn-On Delay Time	t _{d(on)}			5.3			
Turn-On Rise Time	t _r	V _{DD} =10V, V _{GS} =4.5V,		10.7			
Turn-Off Delay Time	t _{d(off)}	$R_{GEN}=6\Omega$, $I_D=3.6A$		17		ns ns	
Turn-Off Fall Time	t _f			7.1			

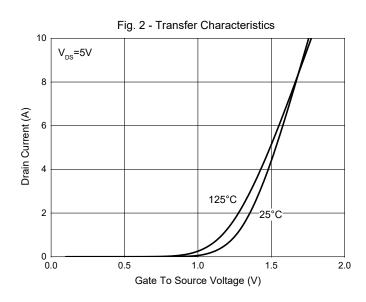


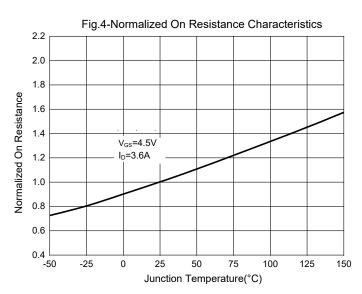
Curve Characteristics

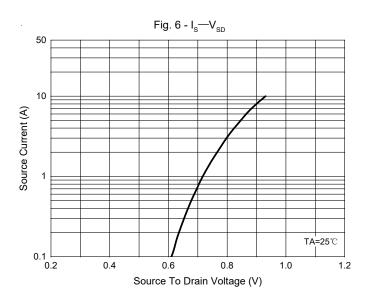






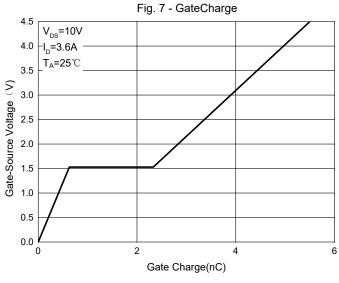


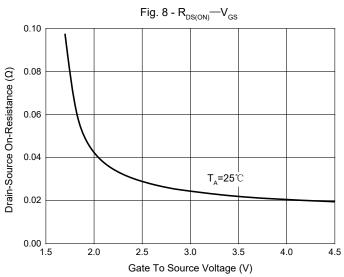


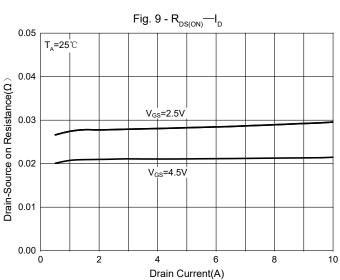


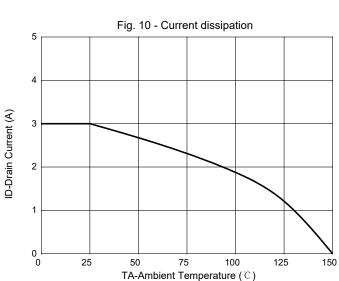


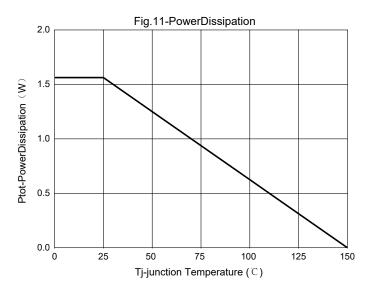
Curve Characteristics





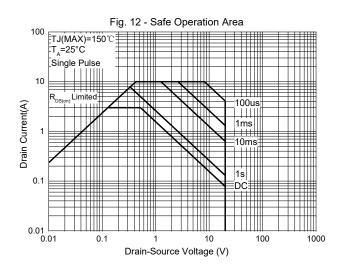


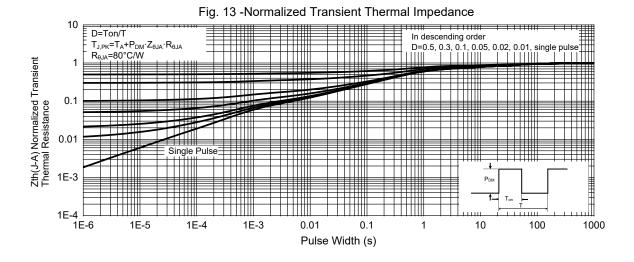






Curve Characteristics





Rev.4-1-12222022 5/6 MCCSEMI.COM



Ordering Information

Device	Packing	
SI2302-TP	Tape&Reel: 3Kpcs/Reel	

Revision History

Datasheet status	Version No	Release date	Update content
New product datasheet	Rev4-1	20221222	

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